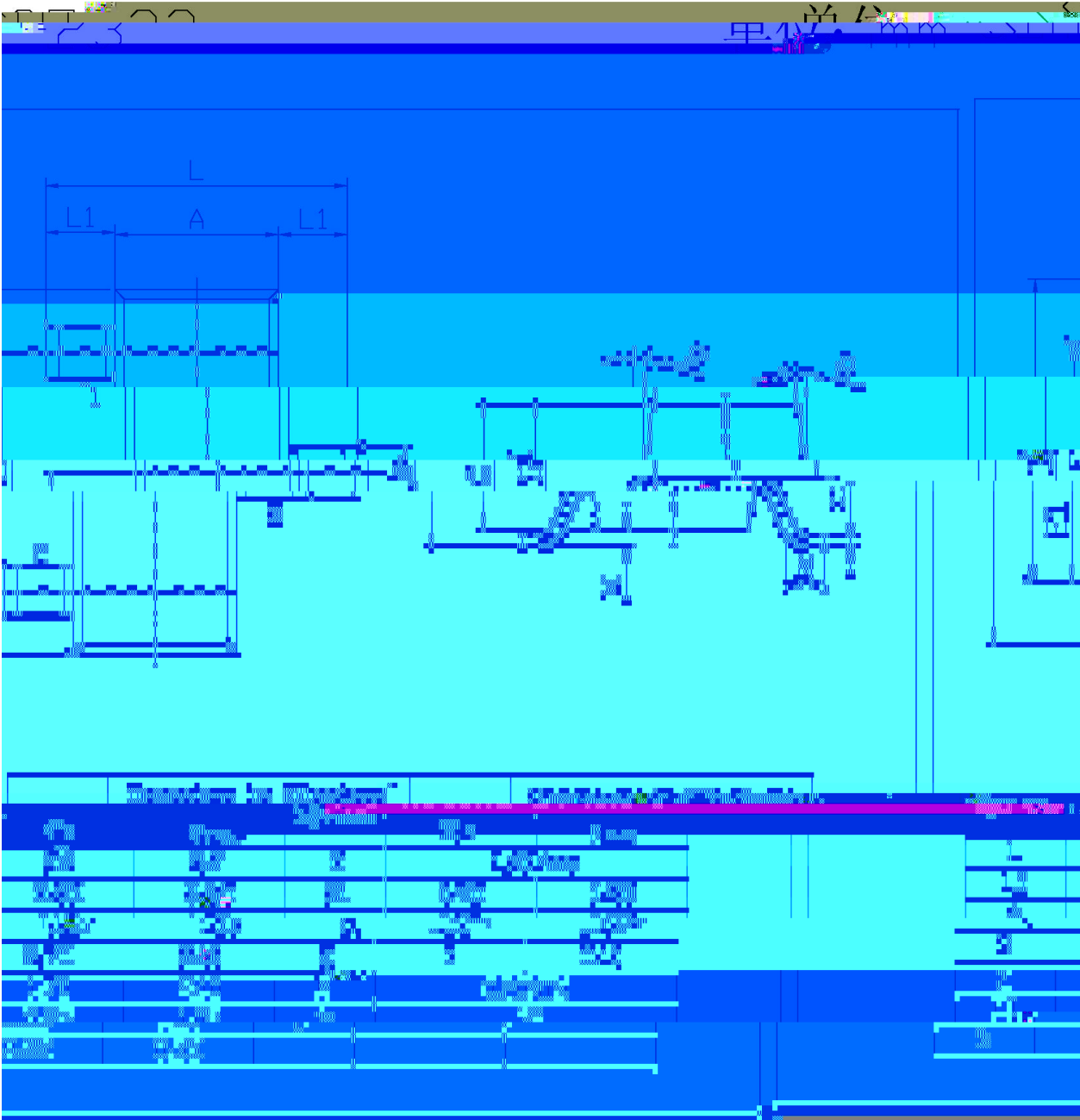
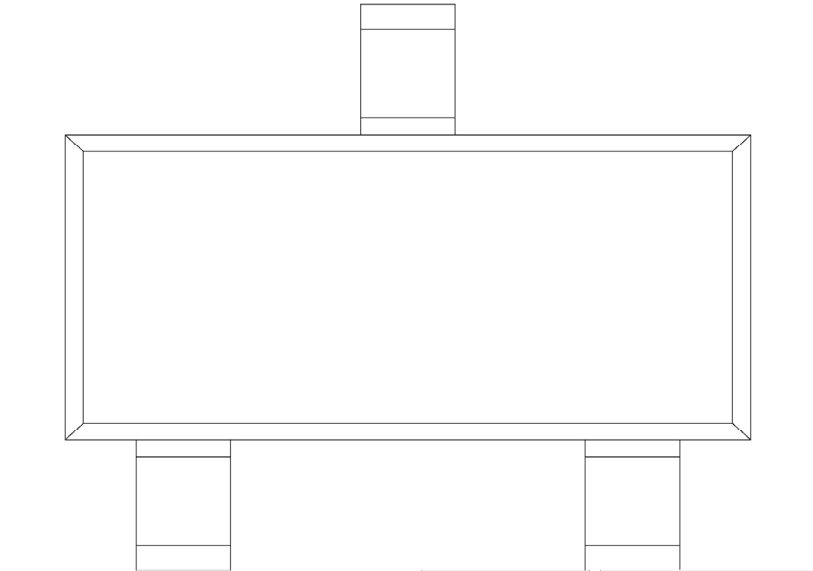


Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	30	V
Collector to Emitter Voltage	V_{CEO}	20	V
Emitter to Base Voltage	V_{EBO}	3.0	V
Collector Current	I_C	15	mA
Collector Power Dissipation	P_C	100	mW
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

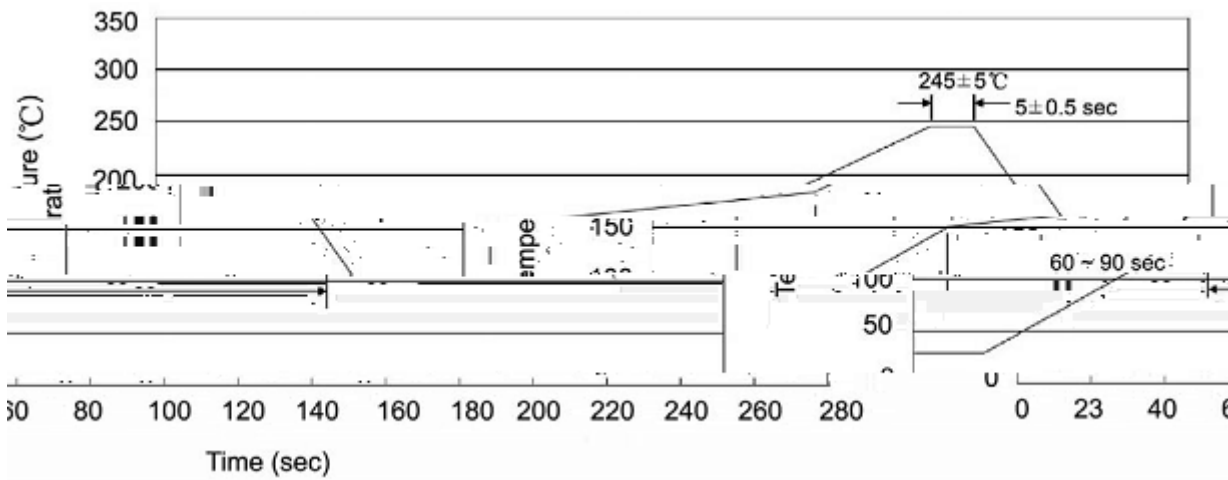
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector- Base Breakdown Voltage	V_{CBO}	$I_C=10\mu A$	30			V
Emitter-Base Breakdown Voltage	V_{EBO}	$I_E=10\mu A$	3.0			V
DC Current Gain	h_{FE}	$V_{CE}=6.0V$ $I_C=1.0mA$	40		260	
Transition Frequency	f_T	$V_{CB}=6.0V$ $I_C=1.0mA$	450	650		MHz
Base to Emitter Voltage	V_{BE}	$V_{CB}=6.0V$ $I_C=1.0mA$		0.72		V
Common Emitter Reverse Transfer Capacitance	C_{re}	$V_{CB}=6.0V$ $I_C=1.0mA$ $f=10.7MHz$		0.8	1.0	PF
Power Gain	P_G	$V_{CB}=6.0V$ $I_C=1.0mA$ $f=100MHz$		24		dB
Noise Figure	NF	$V_{CB}=6.0V$ $I_C=1.0mA$ $f=100MHz$		3.3		dB







Temperature Profile for IR Reflow Soldering(Pb-Free)



℃

1. 预加热: 25~150℃, 时间: 60~90sec;
2. 峰值温度: 245±5℃, 持续时间: 5±0.5sec;
3. 升温速率: 2~10℃/sec.

Note:

1. Preheating: 25~150℃, Time: 60~90sec.
2. Peak Temp.: 245±5℃, Duration: 5±0.5sec.
- 3.